

AMENDMENTS TO THE SPECIFICATION:

Please replace the last paragraph on page 7 with the following amended paragraph:

In each final rinsing step, the cleaning solution was fed at a rate of 15.0 L/min into a 18.24-L cleaning solution tank. Output of the ultrasonic waves was 10. MHz and 4.1 W/cm². Also, measurement of the residual particles was performed for particles of 0.2 μm or larger using a laser scattering type particle counter. The results are shown in FIG. 4 ~~the following graph~~.

Please replace the second and third paragraphs on page 8 with the following amended paragraphs:

Then, under the same experimental conditions (Embodiment 1-1), the prescribed delay time to initiate ultrasonic irradiation was changed in the range of 0-180 sec to determine the influence of the prescribed time on the removal rate of the minute particles. The results are shown in FIG. 5 ~~the following graph~~.

Also, the value of the ~~above graph~~ shown in FIG. 5 was plotted versus the substitution ratio of the cleaning solution with respect to the cleaning solution tank, as shown in FIG. 6 ~~follows~~. In this case the results of the above graph are converted to relative values, with unity defined as the case when the same amount of cleaning solution is fed per unit time (min) into a cleaning solution tank of unit volume (L).

Please replace the first paragraph on page 9 with the following amended paragraph:

As can be seen from the ~~aforementioned~~ results shown in FIGS. 5-6, in order to remove minute particles effectively, it is preferred that the prescribed time be 20-30 sec or longer, and the substitution ratio of the cleaning solution with respect to the cleaning solution tank be 0.4 or higher. Also the values for the residual particle count listed in FIGS. 4-6 ~~Tables 1-3~~ refer to the results measured with respect to 6-inch semiconductor wafers.